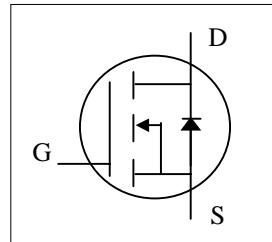




▼ 100% Avalanche Test

▼ Fast Switching

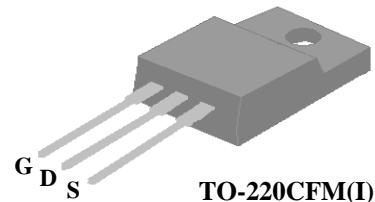
▼ Simple Drive Requirement



BV_{DSS}	600V
$R_{DS(ON)}$	8Ω
I_D	2A

Description

The TO-220CFM package is widely preferred for all commercial-industrial applications. The device is suited for switch mode power supplies ,AC-DC converters and high current high speed switching circuits.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	600	V
V_{GS}	Gate-Source Voltage	± 30	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	2	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	1.26	A
I_{DM}	Pulsed Drain Current ¹	3.6	A
$P_D @ T_c=25^\circ C$	Total Power Dissipation	22	W
	Linear Derating Factor	0.176	W/°C
E_{AS}	Single Pulse Avalanche Energy ²	80	mJ
I_{AR}	Avalanche Current	2	A
E_{AR}	Repetitive Avalanche Energy	2	mJ
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
R_{thj-c}	Maximum Thermal Resistance, Junction-case	5.7	°C/W
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient	62	°C/W



Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=1\text{mA}$	600	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=1\text{mA}$	-	0.6	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=1\text{A}$	-	-	8	Ω
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=250\mu\text{A}$	2	-	4	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=20\text{V}$, $I_{\text{D}}=1\text{A}$	-	0.2	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=600\text{V}$, $V_{\text{GS}}=0\text{V}$	-	-	10	μA
	Drain-Source Leakage Current ($T_j=150^\circ\text{C}$)	$V_{\text{DS}}=480\text{V}$, $V_{\text{GS}}=0\text{V}$	-	-	100	μA
I_{GSS}	Gate-Source Leakage	$V_{\text{GS}}= \pm 30\text{V}$	-	-	± 100	nA
Q_g	Total Gate Charge ³	$I_{\text{D}}=2\text{A}$ $V_{\text{DS}}=480\text{V}$ $V_{\text{GS}}=10\text{V}$	-	14	-	nC
Q_{gs}	Gate-Source Charge		-	2	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge		-	8.5	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time ³	$V_{\text{DS}}=300\text{V}$ $I_{\text{D}}=2\text{A}$ $R_G=10\Omega$, $V_{\text{GS}}=10\text{V}$ $R_D=150\Omega$	-	9.5	-	ns
t_r	Rise Time		-	12	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	21	-	ns
t_f	Fall Time		-	9	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$ $V_{\text{DS}}=25\text{V}$ $f=1.0\text{MHz}$	-	155	-	pF
C_{oss}	Output Capacitance		-	27	-	pF
C_{rss}	Reverse Transfer Capacitance		-	14	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
I_S	Continuous Source Current (Body Diode)	$V_D=V_G=0\text{V}$, $V_S=1.5\text{V}$	-	-	2	A
I_{SM}	Pulsed Source Current (Body Diode) ¹		-	-	3.6	A
V_{SD}	Forward On Voltage ³	$T_j=25^\circ\text{C}$, $I_S=2\text{A}$, $V_{\text{GS}}=0\text{V}$	-	-	1.5	V

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Starting $T_j=25^\circ\text{C}$, $V_{\text{DD}}=50\text{V}$, $L=40\text{mH}$, $R_G=25\Omega$, $I_{\text{AS}}=2\text{A}$.
- 3.Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

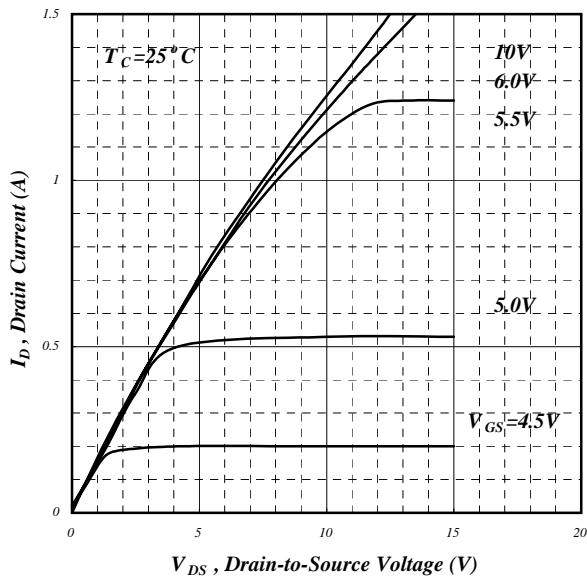


Fig 1. Typical Output Characteristics

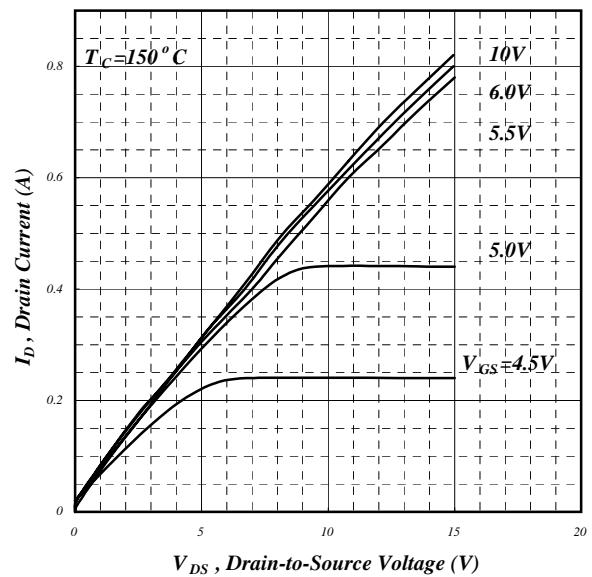


Fig 2. Typical Output Characteristics

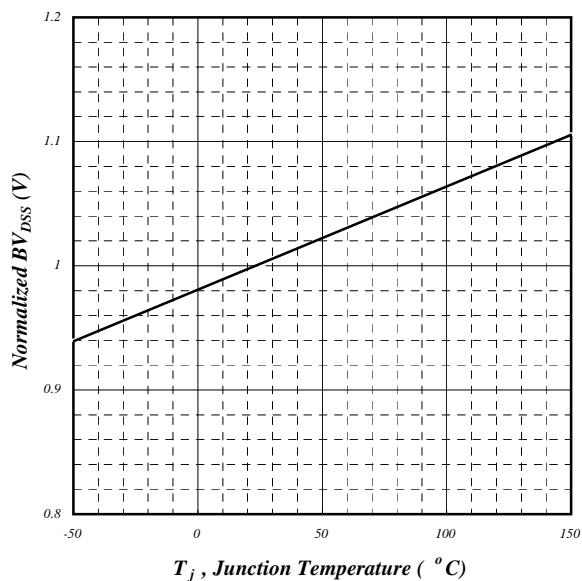
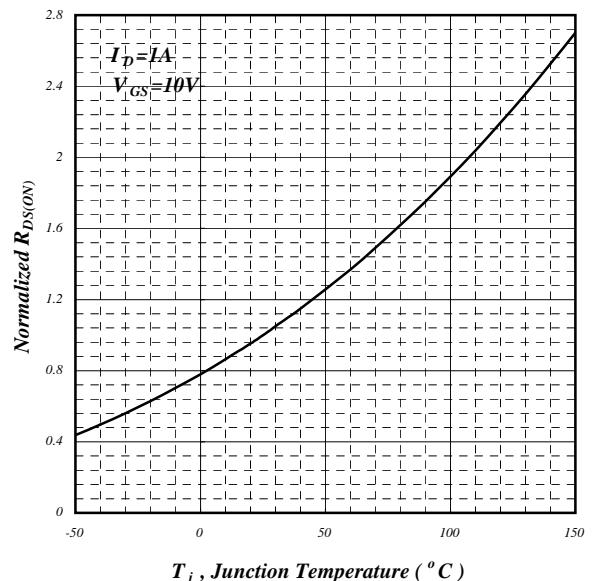
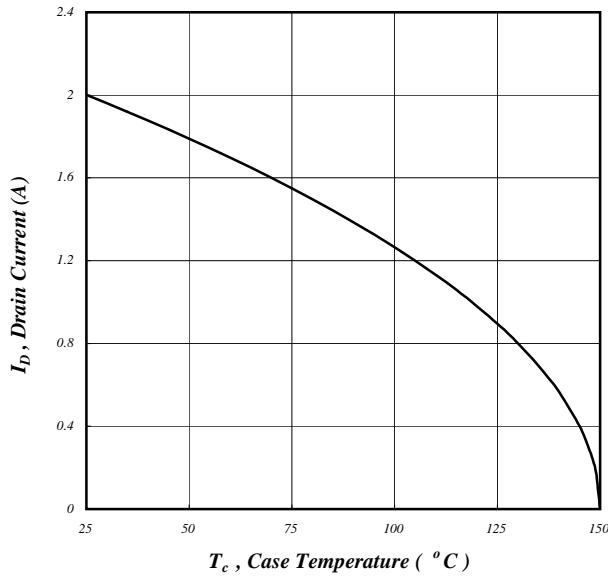
Fig 3. Normalized BV_{DSS} v.s. Junction Temperature

Fig 4. Normalized On-Resistance v.s. Junction Temperature



**Fig 5. Maximum Drain Current v.s.
Case Temperature**

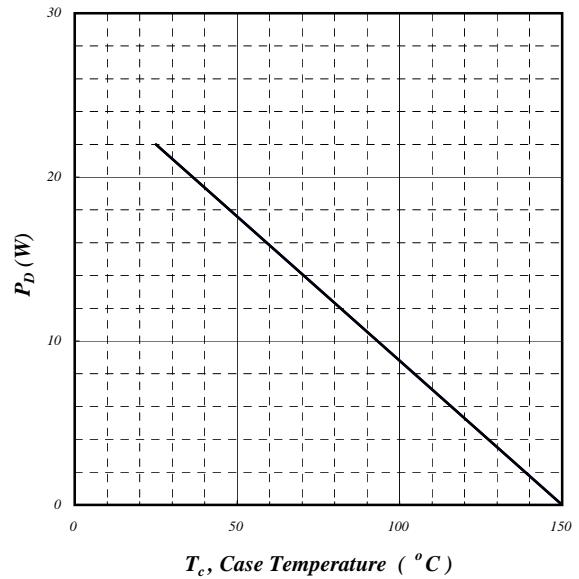


Fig 6. Typical Power Dissipation

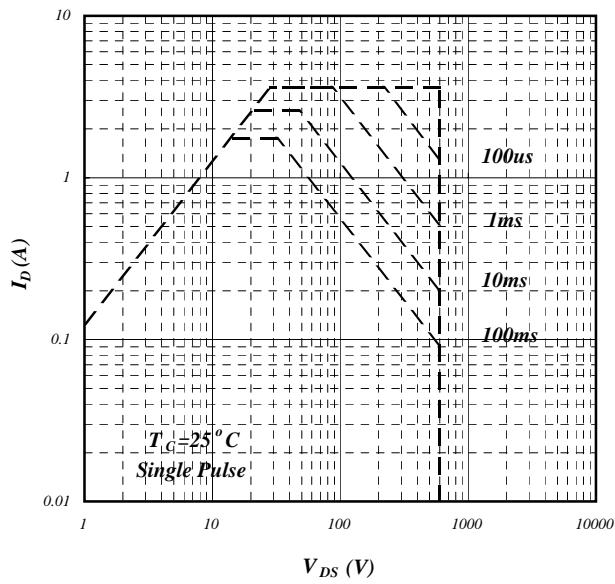


Fig 7. Maximum Safe Operating Area

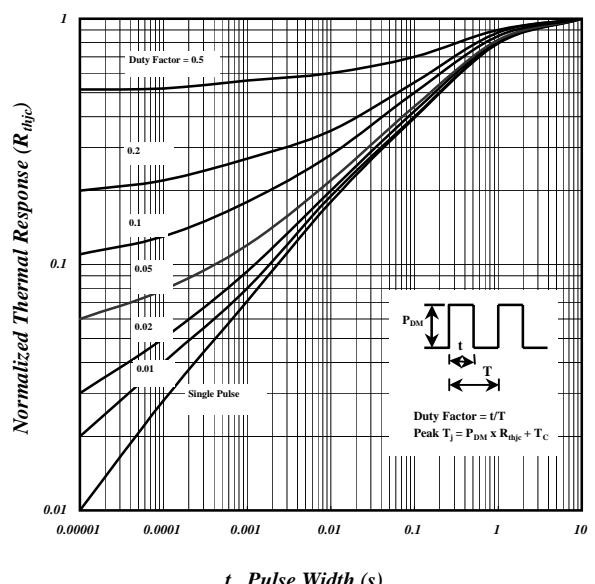


Fig 8. Effective Transient Thermal Impedance

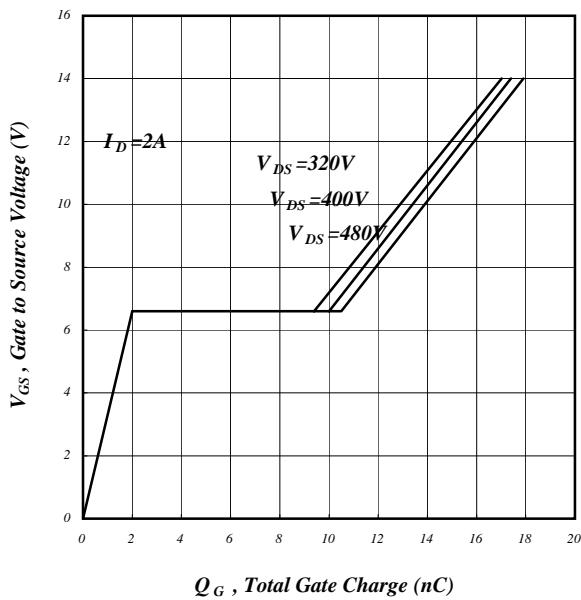


Fig 9. Gate Charge Characteristics

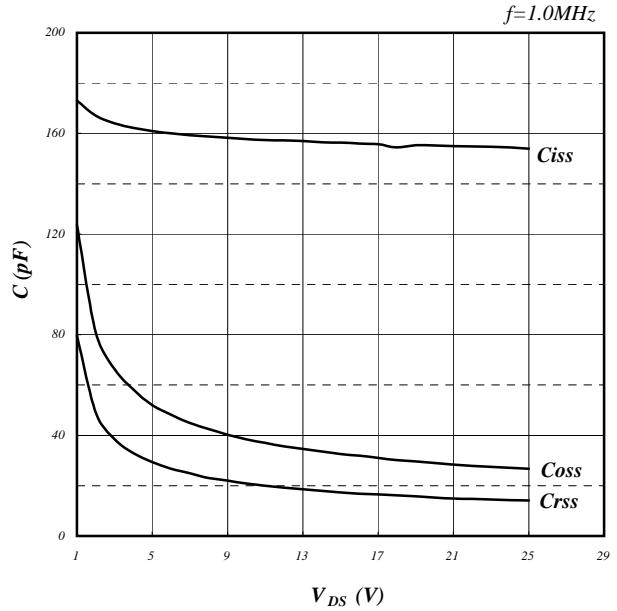


Fig 10. Typical Capacitance Characteristics

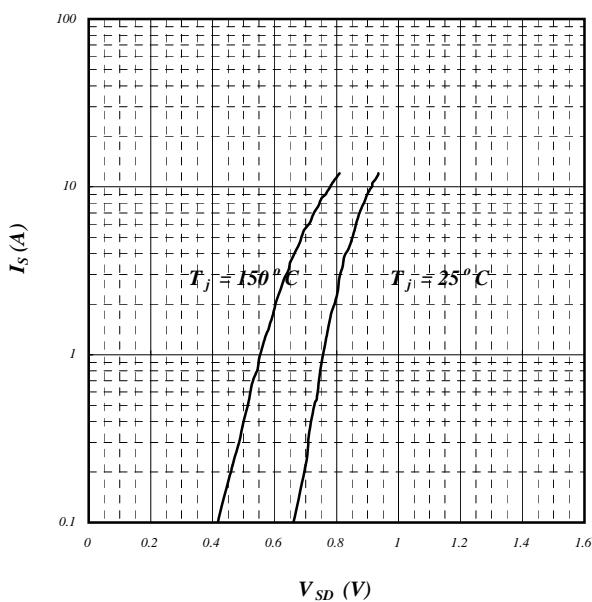


Fig 11. Forward Characteristic of Reverse Diode

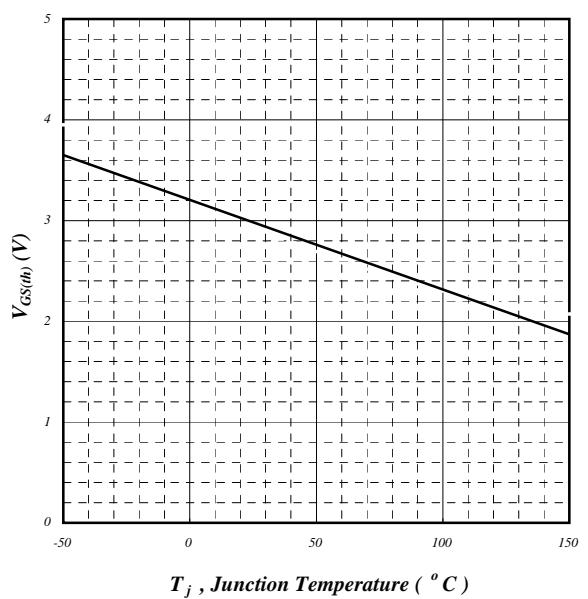
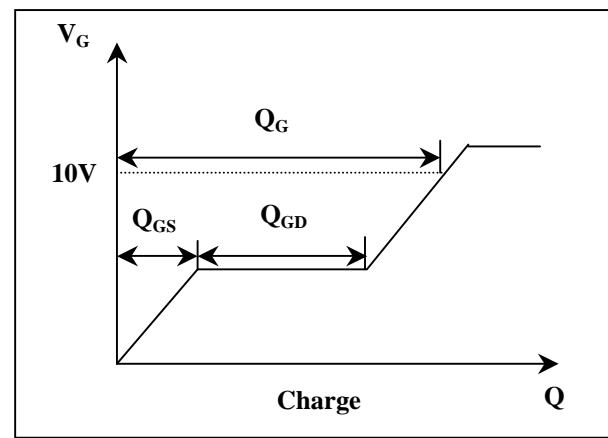
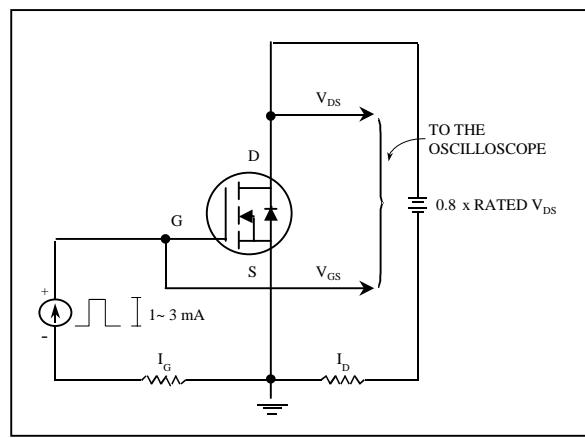
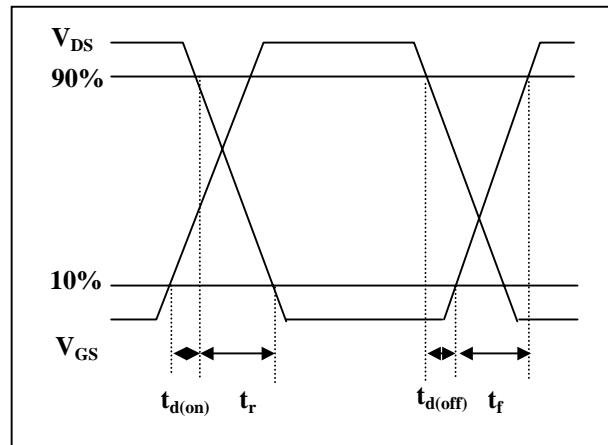
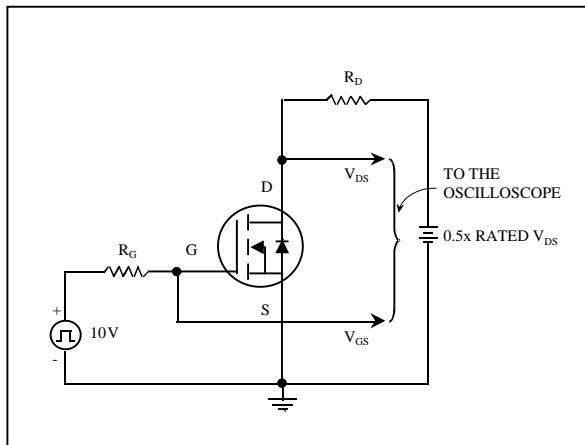


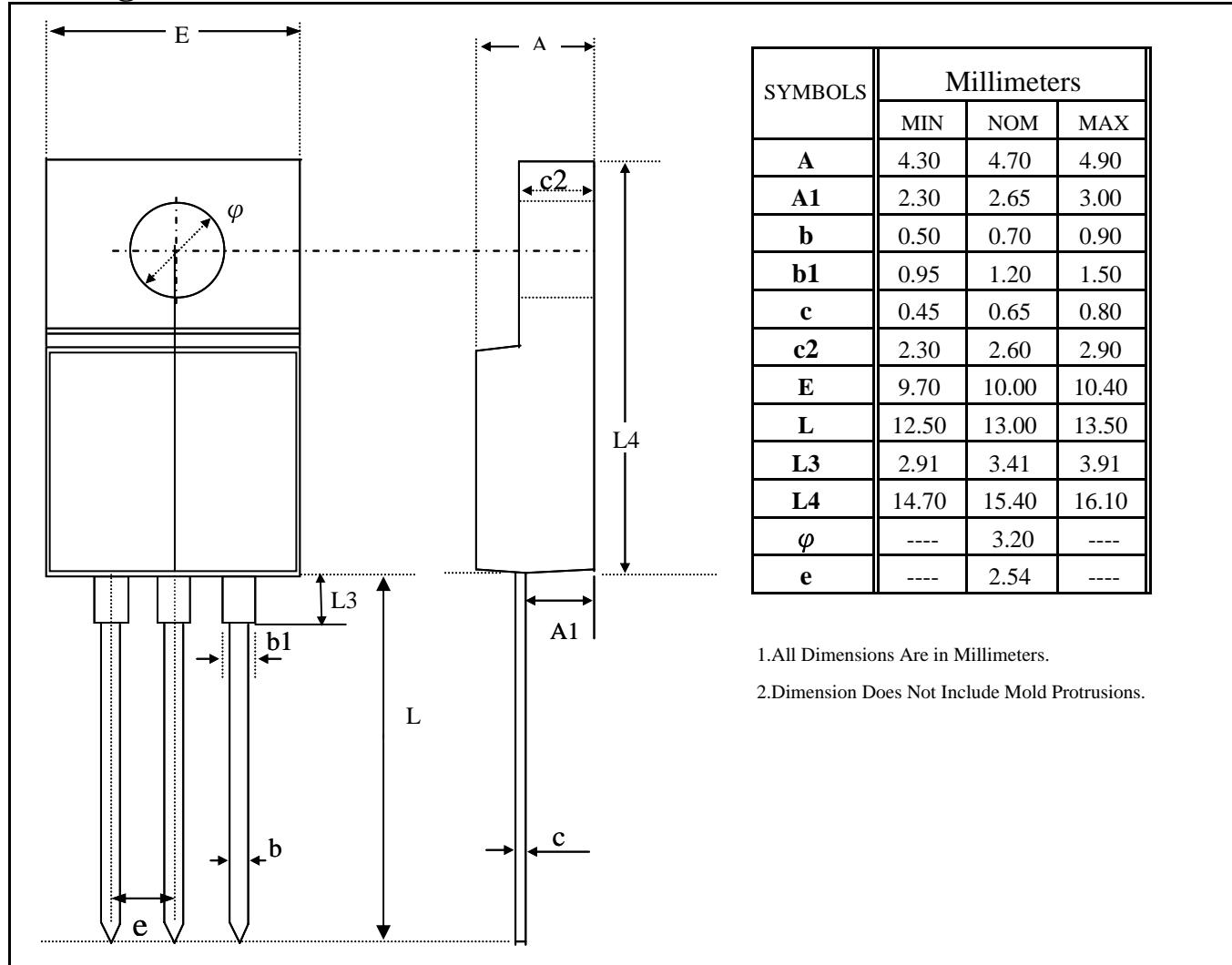
Fig 12. Gate Threshold Voltage v.s. Junction Temperature





ADVANCED POWER ELECTRONICS CORP.

Package Outline : TO-220CFM



Part Marking Information & Packing : TO-220CFM

